

Part Number : 901303108

Series Number : 90130

Product Category : PCB Headers and Receptacles

Product Description : C-Grid III Header, Dual Row, Right-Angle, Shrouded, Fully Loaded, 8 Circuits, Black, 3µm Tin (Sn) over Nickel (Ni)

Status : Active

Documents & Resources

Drawings

Drawing 901303108_sd.pdf

Packaging Design Drawing PK-91814-005-001.pdf

3D Models and Design Files

3D Model 901303108_stp.zip

Specifications

Application Specification 901190001-AS-000.pdf

Packaging Specification PK-90130-001-001.pdf

Product Specification PS-99020-0001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)8585-DC (23 Jan 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C

- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	PCB Headers and Receptacles
Series	90130
Description	C-Grid III Header, Dual Row, Right-Angle, Shrouded, Fully Loaded, 8 Circuits, Black, 3µm Tin (Sn) over Nickel (Ni)
Application	Signal, Wire-to-Board
Component Type	PCB Header
Product Family	C-Grid III Interconnects
Product Name	C-Grid III
UPC	800753706859

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	3.0A
Voltage - Maximum	350V AC/DC

Physical

Breakaway	No
Circuits (Loaded)	8
Circuits (maximum)	8
Color - Resin	Black
Durability (mating cycles max)	30
First Mate / Last Break	No

Flammability	94V-0
Glow-Wire Capable	No
Guide to Mating Part	No
Keying to Mating Part	None
Lock to Mating Part	Yes
Material - Metal	Brass
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Material - Resin	Polyester
Net Weight	1.257/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Tray
PC Tail Length	2.90mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Pitch - Mating Interface	2.54mm
Pitch - Termination Interface	2.54mm
Plating min - Mating	3.048µm
Plating min - Termination	3.048µm
Polarized to Mating Part	Yes
Polarized to PCB	No
Shrouded	Closed Ends
Stackable	No
Temperature Range - Operating	-55° to +125°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	3
Lead-Free Process Capability	WAVE
Max-Cycle	1
Max-Temp	235

Mates With / Use With

Mates with Part(s)

Description	Part Number
C-Grid III Dual Row Crimp Housings	<u>90142</u>
C-Grid III Modular Dual Row Crimp Housings	<u>90143</u>

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